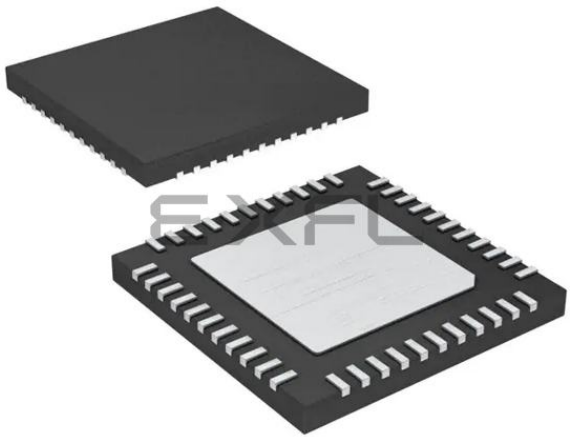

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PSMC, PWM, WDT
Number of I/O	35
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x12b; D/A 1x8b, 3x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1789t-i-ml

4.2 Register Definitions: Configuration Words

REGISTER 4-1: CONFIG1: CONFIGURATION WORD 1

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
FCMEN	IESO	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		$\overline{\text{CPD}}$
bit 13					bit 8

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		FOSC<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **FCMEN:** Fail-Safe Clock Monitor Enable bit
1 = Fail-Safe Clock Monitor and internal/external switchover are both enabled.
0 = Fail-Safe Clock Monitor is disabled

bit 12 **IESO:** Internal External Switchover bit
1 = Internal/External Switchover mode is enabled
0 = Internal/External Switchover mode is disabled

bit 11 **$\overline{\text{CLKOUTEN}}$:** Clock Out Enable bit
If FOSC configuration bits are set to LP, XT, HS modes:
This bit is ignored, CLKOUT function is disabled. Oscillator function on the CLKOUT pin.
All other FOSC modes:
1 = CLKOUT function is disabled. I/O function on the CLKOUT pin.
0 = CLKOUT function is enabled on the CLKOUT pin

bit 10-9 **BOREN<1:0>:** Brown-out Reset Enable bits
11 = BOR enabled
10 = BOR enabled during operation and disabled in Sleep
01 = BOR controlled by SBOREN bit of the BORCON register
00 = BOR disabled

bit 8 **$\overline{\text{CPD}}$:** Data Code Protection bit(1)
1 = Data memory code protection is disabled
0 = Data memory code protection is enabled

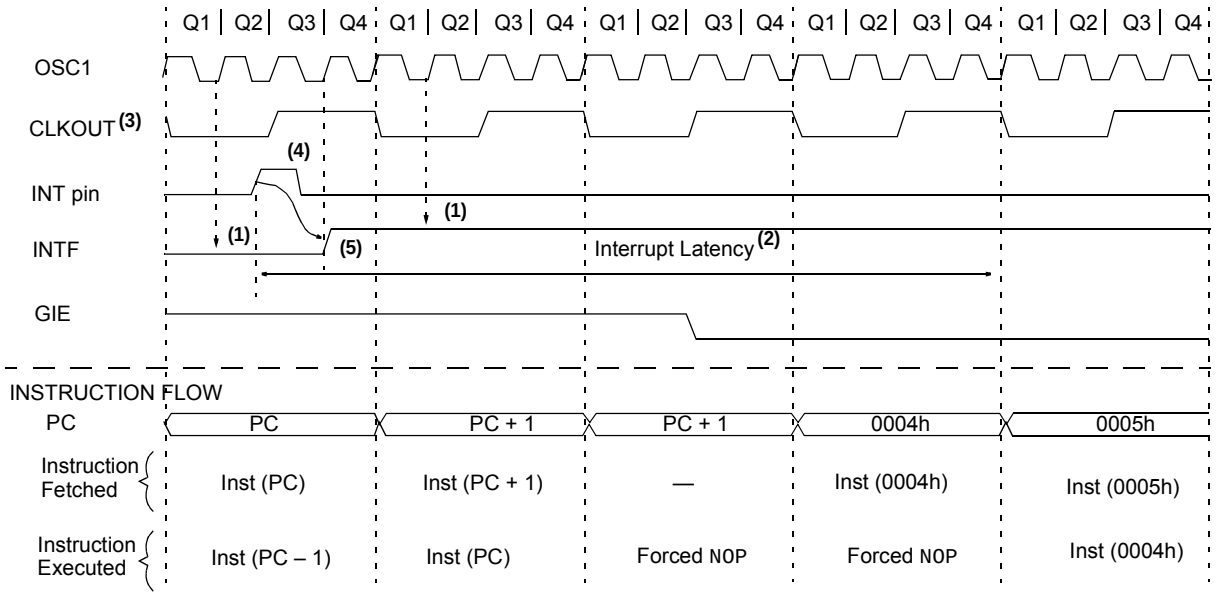
bit 7 **$\overline{\text{CP}}$:** Code Protection bit
1 = Program memory code protection is disabled
0 = Program memory code protection is enabled

bit 6 **MCLRE:** $\overline{\text{MCLR}}$/V_{PP} Pin Function Select bit
If LVP bit = 1:
This bit is ignored.
If LVP bit = 0:
1 = $\overline{\text{MCLR}}$/V_{PP} pin function is $\overline{\text{MCLR}}$; Weak pull-up enabled.
0 = $\overline{\text{MCLR}}$/V_{PP} pin function is digital input; $\overline{\text{MCLR}}$ internally disabled; Weak pull-up under control of WPUE3 bit.

bit 5 **$\overline{\text{PWRTE}}$:** Power-up Timer Enable bit
1 = PWRT disabled
0 = PWRT enabled

bit 4-3 **WDTE<1:0>:** Watchdog Timer Enable bit
11 = WDT enabled
10 = WDT enabled while running and disabled in Sleep
01 = WDT controlled by the SWDTEN bit in the WDTCON register
00 = WDT disabled

FIGURE 8-3: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-5 TCY. Synchronous latency = 3-4 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT not available in all oscillator modes.

4: For minimum width of INT pulse, refer to AC specifications in **Section 31.0 "Electrical Specifications"**".

5: INTF is enabled to be set any time during the Q4-Q1 cycles.

REGISTER 8-6: PIR1: PERIPHERAL INTERRUPT REQUEST REGISTER 1

R/W-0/0	R/W-0/0	R-0/0	R-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **TMR1GIF:** Timer1 Gate Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 6 **ADIF:** ADC Converter Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 5 **RCIF:** EUSART Receive Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 4 **TXIF:** EUSART Transmit Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 3 **SSP1IF:** Synchronous Serial Port (MSSP) Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 2 **CCP1IF:** CCP1 Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 1 **TMR2IF:** Timer2 to PR2 Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 0 **TMR1IF:** Timer1 Overflow Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

Note:	Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE, of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

9.2 Low-Power Sleep Mode

"F" devices contain an internal Low Dropout (LDO) voltage regulator, which allows the device I/O pins to operate at voltages up to 5.5V while the internal device logic operates at a lower voltage. The LDO and its associated reference circuitry must remain active when the device is in Sleep mode. "F" devices allow the user to optimize the operating current in Sleep, depending on the application requirements.

A Low-Power Sleep mode can be selected by setting the VREGPM bit of the VREGCON register. With this bit set, the LDO and reference circuitry are placed in a low-power state when the device is in Sleep.

9.2.1 SLEEP CURRENT VS. WAKE-UP TIME

In the default operating mode, the LDO and reference circuitry remain in the normal configuration while in Sleep. The device is able to exit Sleep mode quickly since all circuits remain active. In Low-Power Sleep mode, when waking up from Sleep, an extra delay time is required for these circuits to return to the normal configuration and stabilize.

The Low-Power Sleep mode is beneficial for applications that stay in Sleep mode for long periods of time. The normal mode is beneficial for applications that need to wake from Sleep quickly and frequently.

9.2.2 PERIPHERAL USAGE IN SLEEP

Some peripherals that can operate in Sleep mode will not operate properly with the Low-Power Sleep mode selected. The LDO will remain in the normal power mode when those peripherals are enabled. The Low-Power Sleep mode is intended for use with these peripherals:

- Brown-Out Reset (BOR)
- Watchdog Timer (WDT)
- External interrupt pin/Interrupt-on-change pins
- Timer1 (with external clock source)

Note:	"LF" devices do not have a configurable Low-Power Sleep mode. "LF" devices are an unregulated device and are always in the lowest power state when in Sleep, with no wake-up time penalty. These devices have a lower maximum V_{DD} and I/O voltage than "F" devices. See **Section 31.0 "Electrical Specifications"** for more information.

12.0 DATA EEPROM AND FLASH PROGRAM MEMORY CONTROL

The data EEPROM and Flash program memory are readable and writable during normal operation (full VDD range). These memories are not directly mapped in the register file space. Instead, they are indirectly addressed through the Special Function Registers (SFRs). There are six SFRs used to access these memories:

- EECON1
- EECON2
- EEDATL
- EEDATH
- EEADRL
- EEADRH

When interfacing the data memory block, EEDATL holds the 8-bit data for read/write, and EEADRL holds the address of the EEDATL location being accessed. These devices have 256 bytes of data EEPROM with an address range from 0h to 0FFh.

When accessing the program memory block, the EEDATH:EEDATL register pair forms a 2-byte word that holds the 14-bit data for read/write, and the EEADRL and EEADRH registers form a 2-byte word that holds the 15-bit address of the program memory location being read.

The EEPROM data memory allows byte read and write. An EEPROM byte write automatically erases the location and writes the new data (erase before write).

The write time is controlled by an on-chip timer. The write/erase voltages are generated by an on-chip charge pump rated to operate over the voltage range of the device for byte or word operations.

Depending on the setting of the Flash Program Memory Self Write Enable bits WRT<1:0> of the Configuration Words, the device may or may not be able to write certain blocks of the program memory. However, reads from the program memory are always allowed.

When the device is code-protected, the device programmer can no longer access data or program memory. When code-protected, the CPU may continue to read and write the data EEPROM memory and Flash program memory.

12.1 EEADRL and EEADRH Registers

The EEADRH:EEADRL register pair can address up to a maximum of 256 bytes of data EEPROM or up to a maximum of 32K words of program memory.

When selecting a program address value, the MSB of the address is written to the EEADRH register and the LSB is written to the EEADRL register. When selecting a EEPROM address value, only the LSB of the address is written to the EEADRL register.

12.1.1 EECON1 AND EECON2 REGISTERS

EECON1 is the control register for EE memory accesses.

Control bit EEPGD determines if the access will be a program or data memory access. When clear, any subsequent operations will operate on the EEPROM memory. When set, any subsequent operations will operate on the program memory. On Reset, EEPROM is selected by default.

Control bits RD and WR initiate read and write, respectively. These bits cannot be cleared, only set, in software. They are cleared in hardware at completion of the read or write operation. The inability to clear the WR bit in software prevents the accidental, premature termination of a write operation.

The WREN bit, when set, will allow a write operation to occur. On power-up, the WREN bit is clear. The WRERR bit is set when a write operation is interrupted by a Reset during normal operation. In these situations, following Reset, the user can check the WRERR bit and execute the appropriate error handling routine.

Interrupt flag bit EEIF of the PIR2 register is set when write is complete. It must be cleared in the software.

Reading EECON2 will read all ‘0’s. The EECON2 register is used exclusively in the data EEPROM write sequence. To enable writes, a specific pattern must be written to EECON2.

REGISTER 12-6: EECON2: EEPROM CONTROL 2 REGISTER

W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0
EEPROM Control Register 2							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
S = Bit can only be set	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **Data EEPROM Unlock Pattern bits**

To unlock writes, a 55h must be written first, followed by an AAh, before setting the WR bit of the EECON1 register. The value written to this register is used to unlock the writes. There are specific timing requirements on these writes. Refer to **Section 12.2.2 "Writing to the Data EEPROM Memory"** for more information.

TABLE 12-3: SUMMARY OF REGISTERS ASSOCIATED WITH DATA EEPROM

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
EECON1	EEPGD	CFGS	LWLO	FREE	WRERR	WREN	WR	RD	128
EECON2	EEPROM Control Register 2 (not a physical register)								129*
EEADRL	EEADRL<7:0>								127
EEADRH	—(1)	EEADRH<6:0>							127
EEDATL	EEDATL<7:0>								127
EEDATH	—	—	EEDATH<5:0>						127
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	97
PIE2	OSFIE	C2IE	C1IE	EEIE	BCL1IE	C4IE	C3IE	CCP2IE	99
PIR2	OSFIF	C2IF	C1IF	EEIF	BCL1IF	C4IF	C3IF	CCP2IF	103

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by data EEPROM module.

* Page provides register information.

2: Unimplemented, read as '1'.

13.4 Register Definitions: PORTA

REGISTER 13-3: PORTA: PORTA REGISTER

R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x	R/W-x/x
RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **RA<7:0>**: PORTA I/O Value bits(1)
1 = Port pin is ≥ V_{IH}
0 = Port pin is ≤ V_{IL}

Note 1: Writes to PORTA are actually written to corresponding LATA register. Reads from PORTA register is return of actual I/O pin values.

REGISTER 13-4: TRISA: PORTA TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **TRISA<7:0>:** PORTA Tri-State Control bits
1 = PORTA pin configured as an input (tri-stated)
0 = PORTA pin configured as an output

REGISTER 13-5: LATA: PORTA DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATA7	LATA6	LATA5	LATA4	LATA3	LATA2	LATA1	LATA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-4 **LATA<7:0>**: PORTA Output Latch Value bits(1)

Note 1: Writes to PORTA are actually written to corresponding LATA register. Reads from PORTA register is return of actual I/O pin values.

13.5 PORTB Registers

13.5.1 DATA REGISTER

PORTB is an 8-bit wide, bidirectional port. The corresponding data direction register is TRISB (Register 13-12). Setting a TRISB bit (= 1) will make the corresponding PORTB pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISB bit (= 0) will make the corresponding PORTB pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 13-1 shows how to initialize an I/O port.

Reading the PORTB register (Register 13-11) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATB).

13.5.2 DIRECTION CONTROL

The TRISB register (Register 13-12) controls the PORTB pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISB register are maintained set when using them as analog inputs. I/O pins configured as analog inputs always read '0'.

13.5.3 OPEN-DRAIN CONTROL

The ODCONB register (Register 13-16) controls the open-drain feature of the port. Open-drain operation is independently selected for each pin. When an ODCONB bit is set, the corresponding port output becomes an open-drain driver capable of sinking current only. When an ODCONB bit is cleared, the corresponding port output pin is the standard push-pull drive capable of sourcing and sinking current.

13.5.4 SLEW RATE CONTROL

The SLRCONB register (Register 13-17) controls the slew rate option for each port pin. Slew rate control is independently selectable for each port pin. When an SLRCONB bit is set, the corresponding port pin drive is slew rate limited. When an SLRCONB bit is cleared, The corresponding port pin drive slews at the maximum rate possible.

13.5.5 INPUT THRESHOLD CONTROL

The INLVLB register (Register 13-18) controls the input voltage threshold for each of the available PORTB input pins. A selection between the Schmitt Trigger CMOS or the TTL Compatible thresholds is available. The input threshold is important in determining the value of a read of the PORTB register and also the level at which an interrupt-on-change occurs, if that feature is enabled. See **Section TABLE 31-1: "Supply Voltage"** for more information on threshold levels.

Note:	Changing the input threshold selection should be performed while all peripheral modules are disabled. Changing the threshold level during the time a module is active may inadvertently generate a transition associated with an input pin, regardless of the actual voltage level on that pin.

13.5.6 ANALOG CONTROL

The ANSELB register (Register 13-14) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSELB bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSELB bits has no effect on digital output functions. A pin with TRIS clear and ANSELB set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

Note:	The ANSELB bits default to the Analog mode after Reset. To use any pins as digital general purpose or peripheral inputs, the corresponding ANSEL bits must be initialized to '0' by user software.

TABLE 17-2: ADC OUTPUT RESULTS FORMAT

Absolute ADC Value (decimal)	Sign and Magnitude Result ADFM = 0, ADRMD = 0		2's Compliment Result ADFM = 1, ADRMD = 0	
	ADRESH (ADRES<15:8>)	ADRESL (ADRES<7:0>)	ADRESH (ADRES<15:8>)	ADRESL (ADRES<7:0>)
+ 4095	1111 1111	1111 0000	0000 1111	1111 1111
+ 2355	1001 0011	0011 0000	0000 1001	0011 0011
+ 0001	0000 0000	0001 0000	0000 0000	0000 0001
0000	0000 0000	0000 0000	0000 0000	0000 0000
- 0001	0000 0000	0001 0001	1111 1111	1111 1111
- 4095	1111 1111	1111 0001	1111 0000	0000 0001
- 4096	0000 0000	0000 0001	1111 0000	0000 0000

Note 1: For the RSD ADC, the raw 13-bits from the ADC is presented in 2's compliment format, so no data translation is required for 2's compliment results.

2: For the SAR ADC, the raw 13-bits from the ADC is presented in sign and magnitude format, so no data translation is required for sign and magnitude results

25.3.6 PWM RESOLUTION

The resolution determines the number of available duty cycles for a given period. For example, a 10-bit resolution will result in 1024 discrete duty cycles, whereas an 8-bit resolution will result in 256 discrete duty cycles.

The maximum PWM resolution is ten bits when PR2 is 255. The resolution is a function of the PR2 register value as shown by Equation 25-4.

EQUATION 25-4: PWM RESOLUTION

$$Resolution = \frac{log[4(PR2 + 1)]}{log(2)} \ bits$$

Note: If the pulse width value is greater than the period the assigned PWM pin(s) will remain unchanged.

TABLE 25-1: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (FOSC = 20 MHz)

PWM Frequency	1.22 kHz	4.88 kHz	19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescale	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	6.6

TABLE 25-2: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (FOSC = 8 MHz)

PWM Frequency	1.22 kHz	4.90 kHz	19.61 kHz	76.92 kHz	153.85 kHz	200.0 kHz
Timer Prescale	16	4	1	1	1	1
PR2 Value	0x65	0x65	0x65	0x19	0x0C	0x09
Maximum Resolution (bits)	8	8	8	6	5	5

25.3.7 OPERATION IN SLEEP MODE

In Sleep mode, the TMR2 register will not increment and the state of the module will not change. If the CCPx pin is driving a value, it will continue to drive that value. When the device wakes up, TMR2 will continue from its previous state.

25.3.8 CHANGES IN SYSTEM CLOCK FREQUENCY

The PWM frequency is derived from the system clock frequency. Any changes in the system clock frequency will result in changes to the PWM frequency. See **Section 6.0 "Oscillator Module (with Fail-Safe Clock Monitor)"** for additional details.

25.3.9 EFFECTS OF RESET

Any Reset will force all ports to Input mode and the CCP registers to their Reset states.

26.8 PSMC Synchronization

It is possible to synchronize the periods of two or more PSMC modules together, provided that all modules are on the same device.

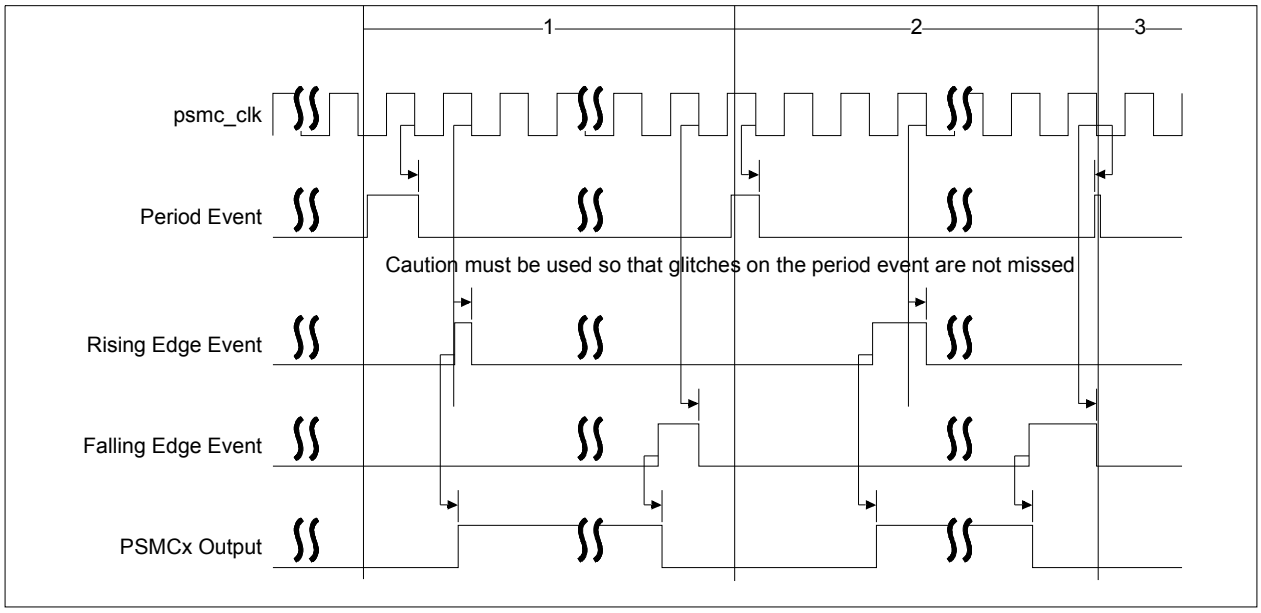
Synchronization is achieved by sending a sync signal from the master PSMC module to the desired slave modules. This sync signal generates a period event in each slave module, thereby aligning all slaves with the master. This is useful when an application requires different PWM signal generation from each module but the waveforms must be consistent within a PWM period.

26.8.1 SYNCHRONIZATION SOURCES

The synchronization source can be any PSMC module on the same device. For example, in a device with two PSMC modules, the possible sources for each device is as shown below:

- Sources for PSMC1
  - PSMC2
- Sources for PSMC2
  - PSMC1

FIGURE 26-21: PSMC SYNCHRONIZATION - SYNC OUTPUT TO PIN



26.8.1.1 PSMC Internal Connections

The sync signal from the master PSMC module is essentially that modules period event trigger. The slave PSMC modules reset their PSMCxTMR with the sync signal instead of their own period event.

Enabling a module as a slave recipient is done with the PxSYNC bits of the PSMC Synchronization Control (PSMCxSYNC) registers; registers 26-3 and 26-4.

26.8.1.2 Phase Offset Synchronization

The synchronization output signal from the PSMC module is selectable. The sync_out source may be either:

- Period Event
- Rising Event

Source selection is made with the PxPOFST bit of the PSMCxSYNC registers, registers 26-3, 26-4 and 26-7.

When the PxPOFST bit is set, the sync_out signal comes from the rising event and the period event replaces the rising event as the start of the active drive period. When PxPOFST is set, duty cycles of up to 100% are achievable in both the slave and master.

When PXPOFST is clear, the sync_out signal comes from the period event. When PxPOFST is clear, rising events that start after the period event remove the equivalent start delay percentage from the maximum 100% duty cycle.

26.8.1.3 Synchronization Skid

When the sync_out source is the Period Event, the slave synchronous rising and falling events will lag by one psmc_clk period. When the sync_out source is the Rising Event, the synchronous events will lag by two clock periods. To compensate for this, the values in PHH:PHL and DCH:DCL registers can be reduced by the number of lag cycles.

27.6 I²C Master Mode

Master mode is enabled by setting and clearing the appropriate SSPM bits in the SSPCON1 register and by setting the SSPEN bit. In Master mode, the SDA and SCK pins must be configured as inputs. The MSSP peripheral hardware will override the output driver TRIS controls when necessary to drive the pins low.

Master mode of operation is supported by interrupt generation on the detection of the Start and Stop conditions. The Stop (P) and Start (S) bits are cleared from a Reset or when the MSSP module is disabled. Control of the I²C bus may be taken when the P bit is set, or the bus is Idle.

In Firmware Controlled Master mode, user code conducts all I²C bus operations based on Start and Stop bit condition detection. Start and Stop condition detection is the only active circuitry in this mode. All other communication is done by the user software directly manipulating the SDA and SCL lines.

The following events will cause the SSP Interrupt Flag bit, SSP1IF, to be set (SSP interrupt, if enabled):

- Start condition detected
- Stop condition detected
- Data transfer byte transmitted/received
- Acknowledge transmitted/received
- Repeated Start generated

Note 1: The MSSP module, when configured in I²C Master mode, does not allow queuing of events. For instance, the user is not allowed to initiate a Start condition and immediately write the SSPBUF register to initiate transmission before the Start condition is complete. In this case, the SSPBUF will not be written to and the WCOL bit will be set, indicating that a write to the SSPBUF did not occur

Note 1: Master mode suspends Start/Stop detection when sending the Start/Stop condition by means of the SEN/PEN control bits. The SSPxIF bit is set at the end of the Start/Stop generation when hardware clears the control bit.

27.6.1 I²C MASTER MODE OPERATION

The master device generates all of the serial clock pulses and the Start and Stop conditions. A transfer is ended with a Stop condition or with a Repeated Start condition. Since the Repeated Start condition is also the beginning of the next serial transfer, the I²C bus will not be released.

In Master Transmitter mode, serial data is output through SDA, while SCL outputs the serial clock. The first byte transmitted contains the slave address of the receiving device (7 bits) and the Read/Write (R/$\overline{W}$) bit. In this case, the R/$\overline{W}$ bit will be logic '0'. Serial data is transmitted eight bits at a time. After each byte is transmitted, an Acknowledge bit is received. Start and Stop conditions are output to indicate the beginning and the end of a serial transfer.

In Master Receive mode, the first byte transmitted contains the slave address of the transmitting device (7 bits) and the R/$\overline{W}$ bit. In this case, the R/$\overline{W}$ bit will be logic '1'. Thus, the first byte transmitted is a 7-bit slave address followed by a '1' to indicate the receive bit. Serial data is received via SDA, while SCL outputs the serial clock. Serial data is received eight bits at a time. After each byte is received, an Acknowledge bit is transmitted. Start and Stop conditions indicate the beginning and end of transmission.

A Baud Rate Generator is used to set the clock frequency output on SCL. See **Section 27.7 "Baud Rate Generator"** for more detail.

27.7 BAUD RATE GENERATOR

The MSSP module has a Baud Rate Generator available for clock generation in both I^2C and SPI Master modes. The Baud Rate Generator (BRG) reload value is placed in the SSPADD register (Register 27-6). When a write occurs to SSPBUF, the Baud Rate Generator will automatically begin counting down.

Once the given operation is complete, the internal clock will automatically stop counting and the clock pin will remain in its last state.

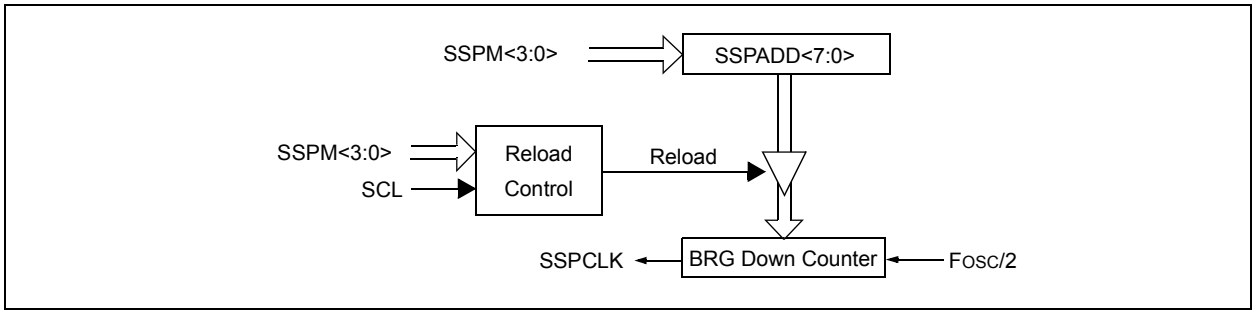
An internal signal “Reload” in Figure 27-39 triggers the value from SSPADD to be loaded into the BRG counter. This occurs twice for each oscillation of the module clock line. The logic dictating when the reload signal is asserted depends on the mode the MSSP is being operated in.

Table 27-4 demonstrates clock rates based on instruction cycles and the BRG value loaded into SSPADD.

EQUATION 27-1:

$$F_{CLOCK} = \frac{F_{OSC}}{(SSPxADD + 1)(4)}$$

FIGURE 27-40: BAUD RATE GENERATOR BLOCK DIAGRAM



Note: Values of 0x00, 0x01 and 0x02 are not valid for SSPADD when used as a Baud Rate Generator for I^2C. This is an implementation limitation.

TABLE 27-4: MSSP CLOCK RATE W/BRG

FOSC	FCY	BRG Value	FCLOCK (2 Rollovers of BRG)
32 MHz	8 MHz	13h	400 kHz(1)
32 MHz	8 MHz	19h	308 kHz
32 MHz	8 MHz	4Fh	100 kHz
16 MHz	4 MHz	09h	400 kHz(1)
16 MHz	4 MHz	0Ch	308 kHz
16 MHz	4 MHz	27h	100 kHz
4 MHz	1 MHz	09h	100 kHz

Note 1: Refer to the I/O port electrical and timing specifications in Table 31-9 and Figure 31-7 to ensure the system is designed to support the I/O timing requirements.

REGISTER 27-4: SSPCON3: SSP CONTROL REGISTER 3

R-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
ACKTIM	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **ACKTIM:** Acknowledge Time Status bit (I^2C mode only)**(3)**
1 = Indicates the I^2C bus is in an Acknowledge sequence, set on 8^{TH} falling edge of SCL clock
0 = Not an Acknowledge sequence, cleared on 9^{TH} rising edge of SCL clock

bit 6 **PCIE**: Stop Condition Interrupt Enable bit (I^2C Slave mode only)
1 = Enable interrupt on detection of Stop condition
0 = Stop detection interrupts are disabled**(2)**

bit 5 **SCIE**: Start Condition Interrupt Enable bit (I^2C Slave mode only)
1 = Enable interrupt on detection of Start or Restart conditions
0 = Start detection interrupts are disabled**(2)**

bit 4 **BOEN:** Buffer Overwrite Enable bit
In SPI Slave mode:**(1)**
1 = SSPBUF updates every time that a new data byte is shifted in ignoring the BF bit
0 = If new byte is received with BF bit of the SSPSTAT register already set, SSPOV bit of the SSPCON1 register is set, and the buffer is not updated
In I^2C Master mode and SPI Master mode:
This bit is ignored.
In I^2C Slave mode:
1 = SSPBUF is updated and $\overline{ACK}$ is generated for a received address/data byte, ignoring the state of the SSPOV bit only if the BF bit = 0.
0 = SSPBUF is only updated when SSPOV is clear

bit 3 **SDAHT:** SDA Hold Time Selection bit (I^2C mode only)
1 = Minimum of 300 ns hold time on SDA after the falling edge of SCL
0 = Minimum of 100 ns hold time on SDA after the falling edge of SCL

bit 2 **SBCDE:** Slave Mode Bus Collision Detect Enable bit (I^2C Slave mode only)
If on the rising edge of SCL, SDA is sampled low when the module is outputting a high state, the BCL1IF bit of the PIR2 register is set, and bus goes idle
1 = Enable slave bus collision interrupts
0 = Slave bus collision interrupts are disabled

bit 1 **AHEN:** Address Hold Enable bit (I^2C Slave mode only)
1 = Following the 8th falling edge of SCL for a matching received address byte; CKP bit of the SSPCON1 register will be cleared and the SCL will be held low.
0 = Address holding is disabled

bit 0 **DHEN:** Data Hold Enable bit (I^2C Slave mode only)
1 = Following the 8th falling edge of SCL for a received data byte; slave hardware clears the CKP bit of the SSPCON1 register and SCL is held low.
0 = Data holding is disabled

Note 1: For daisy-chained SPI operation; allows the user to ignore all but the last received byte. SSPOV is still set when a new byte is received and BF = 1, but hardware continues to write the most recent byte to SSPBUF.
2: This bit has no effect in Slave modes that Start and Stop condition detection is explicitly listed as enabled.
3: The ACKTIM Status bit is only active when the AHEN bit or DHEN bit is set.

TABLE 31-10: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET PARAMETERS

Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
30	TMCL	$\overline{MCLR}$ Pulse Width (low)	2 5	— —	— —	μs μs	VDD = 3.3-5V, -40°C to +85°C VDD = 3.3-5V
31	TWDTLP	Low-Power Watchdog Timer Time-out Period	10	16	27	ms	VDD = 3.3V-5V 1:512 Prescaler used
32	TOST	Oscillator Start-up Timer Period(1), (2)	—	1024	—	Tosc	**(Note 3)**
33*	TPWRT	Power-up Timer Period, $\overline{PWRTE}$ = 0	40	65	140	ms	
34*	TIOZ	I/O high-impedance from $\overline{MCLR}$ Low or Watchdog Timer Reset	—	—	2.0	μs	
35	VBOR	Brown-out Reset Voltage	2.55 2.30 1.80	2.70 2.45 1.90	2.85 2.6 2.10	V V V	BORV = 0 BORV =1 (F device) BORV =1 (F device)
35A	VLPBOR	Low-Power Brown-out	1.8	2.1	2.5	V	LPBOR = 1
36*	VHYST	Brown-out Reset Hysteresis	0	25	75	mV	-40°C to +85°C
37*	TBORDC	Brown-out Reset DC Response Time	1	3	5	μs	VDD ≤ VBOR

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: By design.

3: Period of the slower clock.

4: To ensure these voltage tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 μF and 0.01 μF values in parallel are recommended.

TABLE 31-17: 5-BIT DIGITAL-TO-ANALOG CONVERTER (DAC) SPECIFICATIONS

Operating Conditions: V_{DD} = 3V, Temperature = 25°C (unless otherwise stated).							
Param No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
DAC01*	C_{LSB}5	Step Size	—	V_{DD}/32	—	V	
DAC02*	C_{ACC}5	Absolute Accuracy	—	—	± 1/2	LSb	
DAC03*	C_R5	Unit Resistor Value (R)	—	5K	—	Ω	
DAC04*	C_{ST}5	Settling Time(2)	—	—	10	μs	

* These parameters are characterized but not tested.

Note 1: See **Section 32.0 "DC and AC Characteristics Graphs and Charts"** for operating characterization.

2: Settling time measured while DACR<7:0> transitions from '00000' to '01111'.

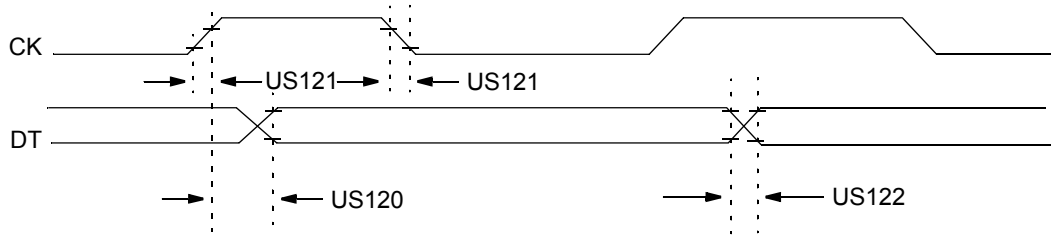
TABLE 31-18: 8-BIT DIGITAL-TO-ANALOG CONVERTER (DAC) SPECIFICATIONS

Operating Conditions: V_{DD} = 3V, Temperature = 25°C (unless otherwise stated).							
Param No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
DAC05*	C_{LSB}8	Step Size	—	V_{DD}/256	—	V	
DAC06*	C_{ACC}8	Absolute Accuracy	—	—	± 1.5	LSb	
DAC07*	C_R8	Unit Resistor Value (R)	—	600	—	Ω	
DAC08*	C_{ST}8	Settling Time(1)	—	—	10	μs	

* These parameters are characterized but not tested.

Note 1: Settling time measured while DACR<7:0> transitions from '0x00' to '0xFF'.

FIGURE 31-14: EUSART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING



Note: Refer to Figure 31-4 for load conditions.

TABLE 31-19: EUSART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Symbol**	**Characteristic**		**Min.**	**Max.**	**Units**	**Conditions**
US120	$T_{CK}H2_{DT}V$	SYNC XMIT (Master and Slave) Clock high to data-out valid	3.0-5.5V	—	80	ns	
			1.8-5.5V	—	100	ns	
US121	T_{CKRF}	Clock out rise time and fall time (Master mode)	3.0-5.5V	—	45	ns	
			1.8-5.5V	—	50	ns	
US122	T_{DTRF}	Data-out rise time and fall time	3.0-5.5V	—	45	ns	
			1.8-5.5V	—	50	ns	

Note: Unless otherwise noted, V_{IN} = 5V, F_{OSC} = 300 kHz, C_{IN} = 0.1 µF, T_A = 25°C.

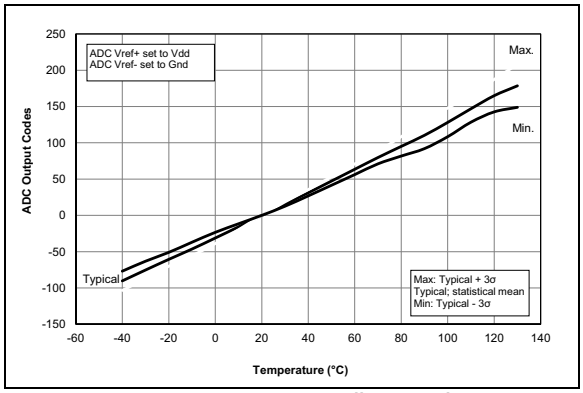


FIGURE 32-103: *Temp. Indicator Slope Normalized to 20°C, High Range, V_{DD} = 3.6V, PIC16F1788/9 Only.*

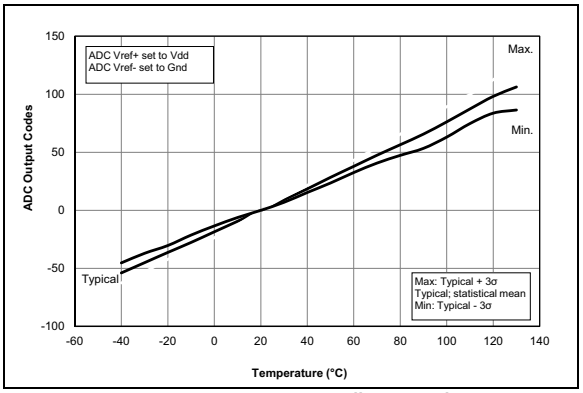


FIGURE 32-104: *Temp. Indicator Slope Normalized to 20°C, Low Range, V_{DD} = 3.0V, PIC16F1788/9 Only.*

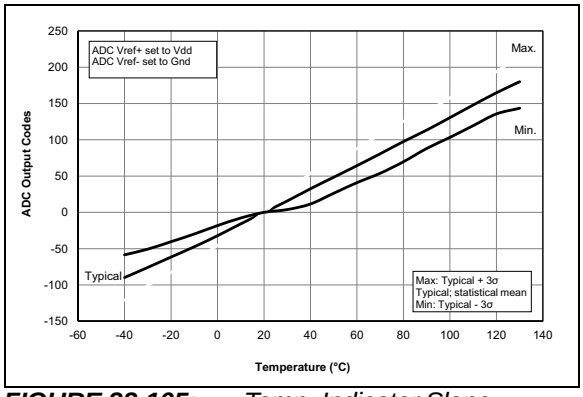


FIGURE 32-105: *Temp. Indicator Slope Normalized to 20°C, Low Range, V_{DD} = 1.8V, PIC16LF1788/9 Only.*

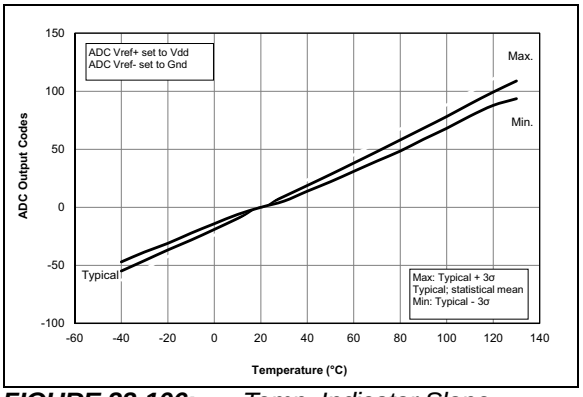


FIGURE 32-106: *Temp. Indicator Slope Normalized to 20°C, Low Range, V_{DD} = 3.0V, PIC16LF1788/9 Only.*

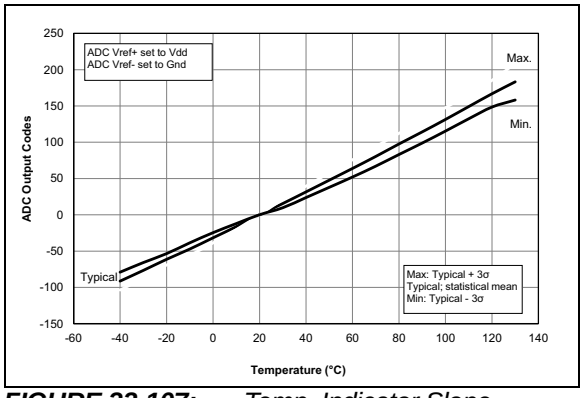


FIGURE 32-107: *Temp. Indicator Slope Normalized to 20°C, High Range, V_{DD} = 3.6V, PIC16LF1788/9 Only.*

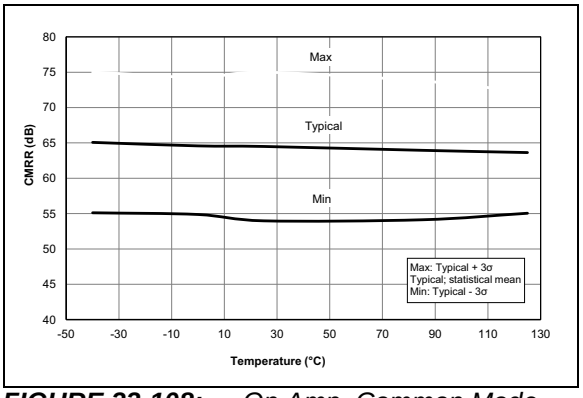
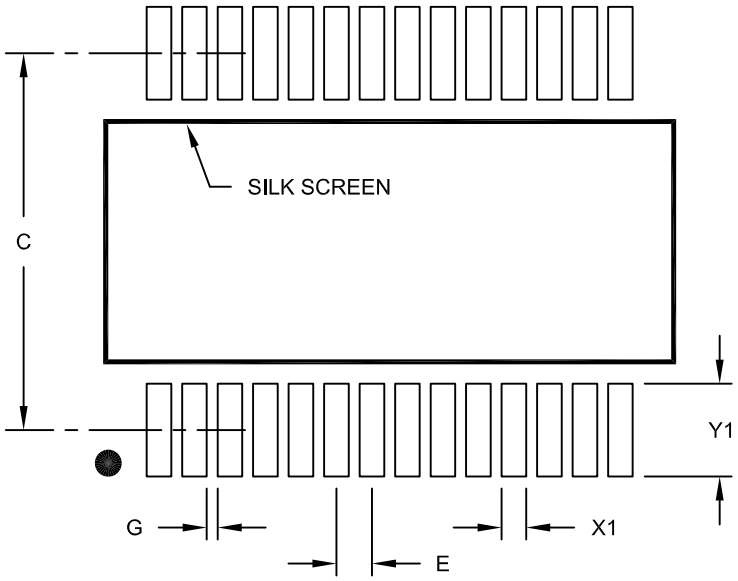


FIGURE 32-108: *Op Amp, Common Mode Rejection Ratio (CMRR), V_{DD} = 3.0V.*

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

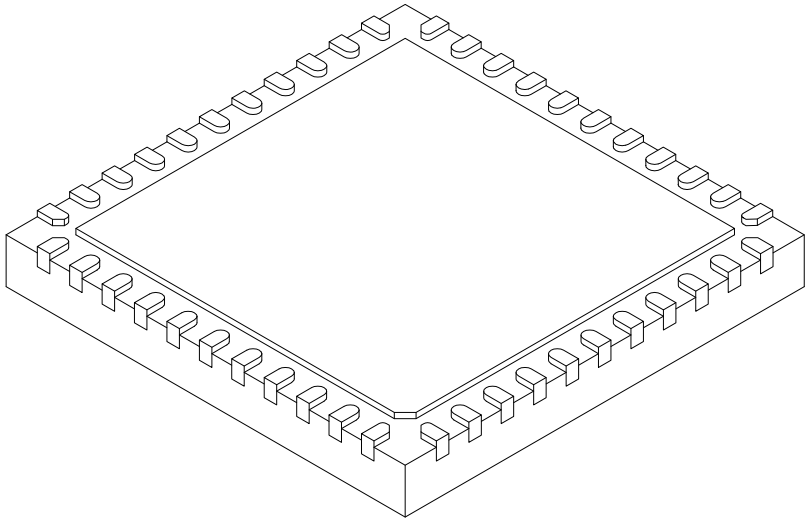
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103C Sheet 2 of 2

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	[X](1)	-	X	/XX	XXX
Device	Tape and Reel Option		Temperature Range	Package	Pattern

Device:	PIC16F1788, PIC16LF1788, PIC16F1789, PIC16LF1789	
Tape and Reel Option:	Blank T	= Standard packaging (tube or tray) = Tape and Reel(1)
Temperature Range:	I E	= -40°C to +85°C (Industrial) = -40°C to +125°C (Extended)
Package:(2)	ML MV P PT SP SO SS	= QFN = UQFN = PDIP = TQFP = SPDIP = SOIC = SSOP
Pattern:	QTP, SQTP, Code or Special Requirements (blank otherwise)	

Examples:

a) PIC16LF1788- I/P
Industrial temperature
PDIP package

b) PIC16F1789- E/SS
Extended temperature,
SSOP package

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

2: Small form-factor packaging options may be available. Please check www.microchip.com/packaging for small-form factor package availability, or contact your local Sales Office.